

# Surface Mount PTC

## 0ZCD Series

2920 Chip  
RoHS6 Compliant & Halogen-Free

Not recommended for new applications. Please use 0ZCF

**0ZCD Series Fuse**
**Maximum Voltage**

6-60V (per table)

**Temperature Range**

-40°C to 85°C

**Agency Approval**

TUV (Std. EN60738-1-1 , Cert. R50102117)  
 UL Component (Std. UL1434, File E305051)  
 UL Conditions of Acceptability:

1. These devices have been investigated for use in safety circuits and are suitable as a limiting device.

2. These devices have been calibrated to limit the current to 8 amps within 5 seconds , per ANSI/NFPA 70, "National Electrical Code"

**Application**

All high-density boards

**Product Features**

2920 Chip Size, Fast Trip Time, High Hold Currents

**Operating (Hold Current) Range**

300mA - 3A

**Electrical Characteristics (23°C)**

	Part Number	Hold Current I <sub>H</sub> , A	Trip Current I <sub>T</sub> , A	Max Time to Trip		Maximum Current I <sub>max</sub> , A	Rated Voltage V <sub>max</sub> , Vdc	Typical Power P <sub>d</sub> , W	Resistance Tolerance		Agency Approvals	
				Current A	Time Sec				R <sub>min</sub> Ohms	R <sub>1max</sub> Ohms	UL US	TUV
A	0ZCD0030FF2C	0.30	0.60	1.5	3.0	10	60	1.5	1.000	4.800	Y	Y
B	0ZCD0050FF2C	0.50	1.00	2.5	4.0	10	60	1.5	0.300	1.400	Y	
C	0ZCD0075FF2C	0.75	1.50	8.0	0.3	40	33	1.5	0.180	1.000	Y	Y
D	0ZCD0100FF2C	1.10	2.20	8.0	0.5	40	33	1.5	0.090	0.410	Y	Y
E	0ZCD0125FF2C	1.25	2.50	8.0	2.0	40	33	1.5	0.050	0.250	Y	Y
F	0ZCD0150FF2C	1.50	3.00	8.0	2.0	40	33	1.5	0.050	0.230	Y	Y
G	0ZCD0185FF2C	1.85	3.70	8.0	2.5	40	33	1.5	0.040	0.150	Y	Y
H	0ZCD0200FF2C	2.00	4.00	8.0	4.5	40	16	1.5	0.035	0.120	Y	Y
I	0ZCD0250FF2C	2.50	5.00	8.0	16.0	40	16	1.5	0.025	0.085	Y	Y
J	0ZCD0260FF2C	2.60	5.20	8.0	20.0	40	6	1.5	0.020	0.075	Y	Y
K	0ZCD0300FF2C	3.00	5.20	8.0	25.0	40	6	1.5	0.010	0.048	Y	Y

- I<sub>H</sub> Hold Current-maximum current at which the device will not trip in still air at 23°C.  
 I<sub>T</sub> Trip current-minimum current at which the device will always trip in still air at 23°C.  
 I<sub>max</sub> Maximum fault current device can withstand without damage at rated voltage (V<sub>max</sub>).  
 V<sub>max</sub> Maximum voltage device can withstand without damage at its rated current.  
 P<sub>d</sub> Typical power dissipated by device when in tripped state in 23°C still air environment.  
 R<sub>min</sub> Minimum device resistance at 23°C.  
 R<sub>1max</sub> Maximum device resistance at 23°C, 1 hour after initial device trip, or after being soldered to PCB in end application.

Specifications subject to change without notice

# Surface Mount PTC

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HF 



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### PTC's – Basic Theory of Operation / "Tripped" Resistance Explanation

Fundamentally, a Bel PTC consists of a block of polymeric material containing conductive filler and bonded between two conductive, planar terminations.

At currents below the device I HOLD rating, AND at temperatures below 100C, the PTC maintains a resistance value below its R1 MAX rating.

As the device's temperature approaches 130C, either due to an increase in ambient temperature or a current exceeding its I TRIP rating, volumetric expansion of the filled polymer breaks apart the majority of conductive pathways across the terminals created by chain contact of adjacent filler particles and device resistance increases sharply by several orders of magnitude.

At the much higher "Tripped" resistance, there is just enough leakage current to allow internal heating to "hold" the device in its tripped state (around 125C) until power is interrupted. Once power is removed, the PTC's core cools and contracts allowing conductive chains to reform and return the device to its low resistance state.

The catalog data for each device specifies a "Typical Power" value. This is the power required to exactly match the heat lost by the tripped device to its ambient surroundings at 23C. By Ohm's Law, power can be stated as:  $W = E^2/R$ . Thus the approximate resistance of a "Tripped" PTC can be determined by:

$R = E^2/W$ , where "E" is the voltage appearing across the PTC (usually the supply's open circuit voltage), and "W" is the **Typical Power** value for the particular PTC.

Since the PPTC acts to maintain a constant internal temperature, its apparent resistance will change based upon applied voltage and, to a lesser degree, ambient conditions. Consider the following example....

A PTC with a **Typical Power** of 1 watt protecting a circuit using a 60V supply will demonstrate an apparent, tripped resistance "R" of:

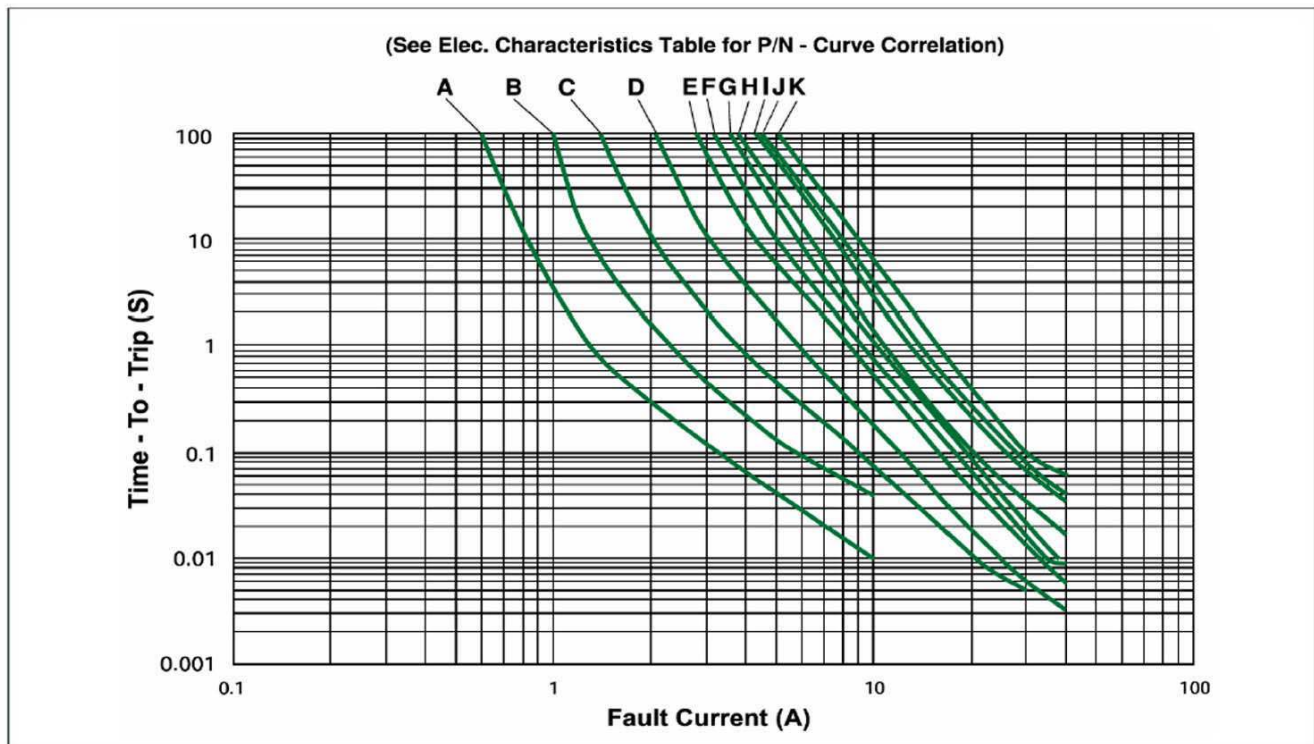
$$R = 60^2/1 = 3,600 \text{ ohms}$$

This same tripped device when used to protect a 12V circuit would now present an apparent resistance of:

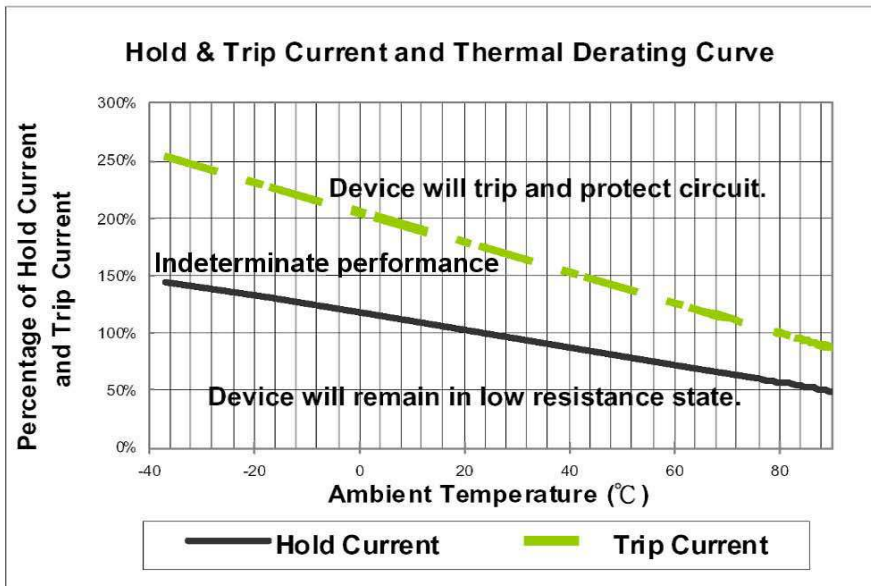
$$R = 12^2/1 = 144 \text{ ohms}$$

The value for Typical Power is "typical" because any physical factors that affect heat loss (such as ambient temperature or air convection) will somewhat alter the level of power that the PTC needs to maintain its internal temperature. In short, PTCs do not exhibit a constant, quantifiable tripped resistance value.

### Typical Time - To - Trip at 23°C



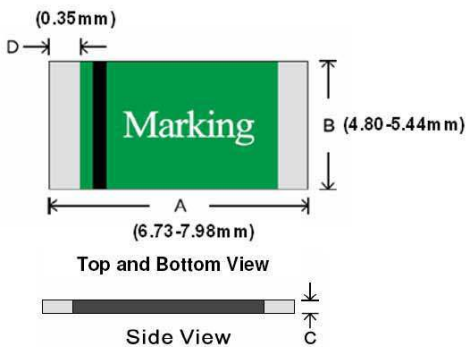
**Thermal Derating Curve**



**Cautionary Notes**

1. Operation beyond the specified maximum ratings or improper use may result in damage and possible electrical arcing and/or flame.
2. These Polymer PTC (PPTC) devices are intended for protection against occasional overcurrent/ overtemperature fault conditions and may not be suitable for use in applications where repeated and/or prolonged fault conditions are anticipated.
3. Avoid contact of PTC device with chemical solvent. Prolonged contact may adversely impact the PTC performance.
4. These PTC devices may not be suitable for use in circuits with a large inductance, as the PTC trip can generate circuit voltage spikes above the PTC rated voltage.
5. These devices are intended for use in DC voltage applications only. Use in AC voltage applications should be first discussed with Bel Fuse engineering.
6. Not recommended for use on potted or conformal coated PCB's. Restriction of free air flow could affect electrical performance and/or result in device failure. Consult Bel Fuse engineering.
7. In the "Indeterminate Performance / grey zone", tripping may occur but cannot be relied upon. For special circumstances considering use within this region, consult Bel Fuse Engineering.

**Mechanical Dimensions**



All dimensions in mm.

C		
Part Number	Min	Max
0ZCD0030FF2C	0.60	1.55
0ZCD0050FF2C	0.60	1.55
0ZCD0075FF2C	0.40	1.15
0ZCD0110FF2C	0.40	1.00
0ZCD0125FF2C	0.40	0.90
0ZCD0150FF2C	0.40	0.90
0ZCD0185FF2C		
Thru	0.30	0.90
0ZCD0300FF2C		

**PTC Marking**

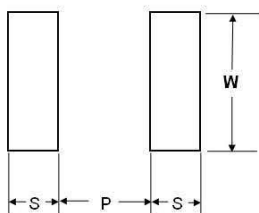


"b", IH code.

Part Number	IH Code
0ZCD0030FF2C	0030
0ZCD0050FF2C	0050
0ZCD0075FF2C	0075
0ZCD0100FF2C	0110
0ZCD0125FF2C	0125
0ZCD0150FF2C	0150
0ZCD0185FF2C	0185
0ZCD0200FF2C	0200
0ZCD0250FF2C	0250
0ZCD0260FF2C	0260
0ZCD0300FF2C	0300

**Pad Layout**

The dimensions in the table below provide the recommended pad layout.



P		S		W	
Nominal	Nominal	Nominal	Nominal	Nominal	Nominal
mm	Inch	mm	Inch	mm	Inch
5.10	0.201	2.30	0.091	5.60	0.221

**Termination Pad Materials**

**Matte Tin-plated Copper**

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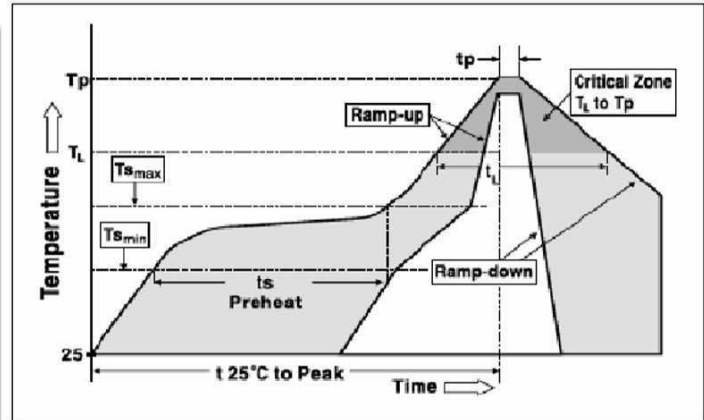
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### Solder Reflow and Rework Recommendations

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (T <sub>smax</sub> to T <sub>p</sub> )	3 °C/second max.
<b>Preheat :</b>	
Temperature Min (T <sub>smin</sub> )	150 °C
Temperature Max (T <sub>smax</sub> )	200 °C
Time (t <sub>smin</sub> to t <sub>smax</sub> )	60-180 seconds
<b>Time maintained above:</b>	
Temperature (T <sub>L</sub> )	217 °C
Time (t <sub>L</sub> )	60-150 seconds
<b>Peak/Classification Temperature (T<sub>p</sub>) :</b>	260 °C
<b>Time within 5°C of actual Peak :</b>	
Temperature (t <sub>p</sub> )	20-40 seconds
<b>Ramp-Down Rate :</b>	6 °C/second max.
<b>Time 25 °C to Peak Temperature :</b>	8 minutes max.



### Solder Reflow

Due to "lead free / RoHS6" construction of these PTC devices, the required Temperature and Dwell Time in the "Soldering" zone of the reflow profile are greater than those used for non-RoHS devices.

1. Recommended reflow methods ; IR , vapor phase oven , hot air oven.
2. Not Recommended For Wave Solder / Direct Immersion.
3. Recommended maximum ; paste thickness is 0.25mm.
4. Devices are compatible with standard industry cleaning solvents and methods.

### Caution

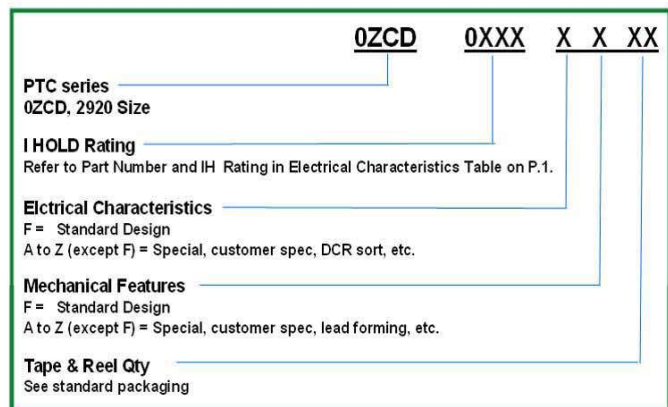
If reflow temperature / dwell times exceed the recommended profile, the electrical performance of the PTC may be affected.

Rework : MIL-STD-202G Method 210F. Test Condition A.

### Standard Packaging

Part Number	Tape/Reel Qty	
0ZCD0030FF2C	2,000	2000 fuses in 7 inches dia. Reel, 8mm wide tape, 4mm pitch, per EIA-481 (equivalent IEC-286 part 3).
0ZCD0050FF2C		
0ZCD0075FF2C		
0ZCD0100FF2C		
0ZCD0125FF2C		
0ZCD0150FF2C		
0ZCD0185FF2C		
0ZCD0200FF2C		
0ZCD0250FF2C		
0ZCD0260FF2C		
0ZCD0300FF2C		

### P/N Explanation and Ordering Information



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